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United States Patent [19]

Matsushima

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[54] **INNER TUBE FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS**

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[73] Assignee: **Tokyo Electron Limited**, Tokyo-To, Japan

[**] Term: **14 Years**

[21] Appl. No.: **74,301**

[22] Filed: **Jul. 24, 1997**

[30] **Foreign Application Priority Data**

Jan. 31, 1997 [JP] Japan 9-2653

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; D15/144, D15/144.1, 199; 414/935–941, 217, 147; 437/247, 546; D23/259, 262, 266

[56] **References Cited**

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[57] **CLAIM**

I claim the ornamental design for inner tube for use in a semiconductor wafer heat processing apparatus, as shown and described.

DESCRIPTION

FIG. **1**: a perspective view of a inner tube for use in a semiconductor wafer heat processing apparatus;

FIG. **2**: a front elevational view thereof, the rear elevational view, the right side view and the left side view are identical with the front view;

FIG. **3**: a top plan view thereof;

FIG. **4**: a bottom plan view thereof; and,

FIG. **5**: a cross sectional view thereof taken along line V-V in FIG. **3**.

1 Claim, 2 Drawing Sheets

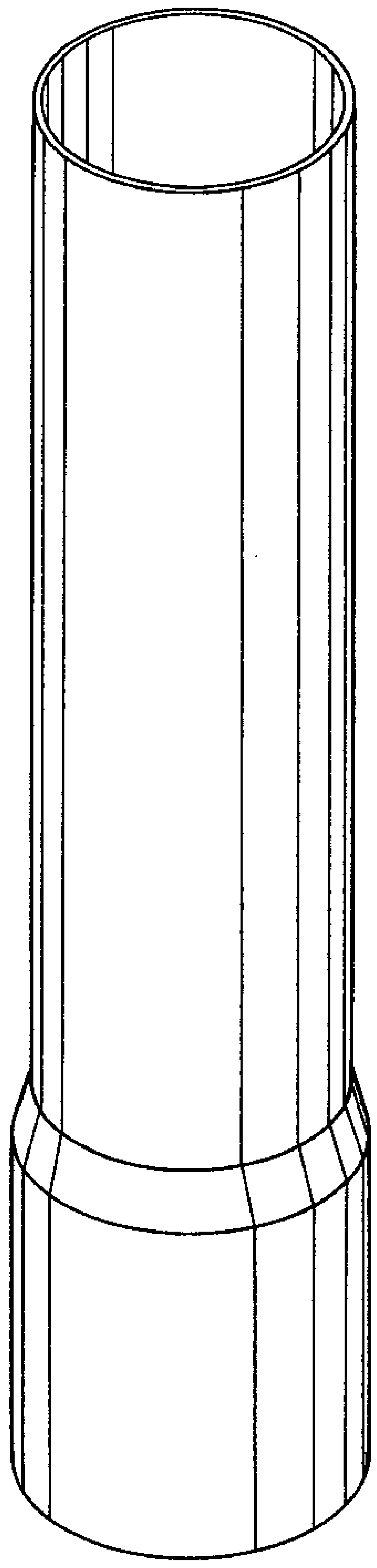

FIG. 1

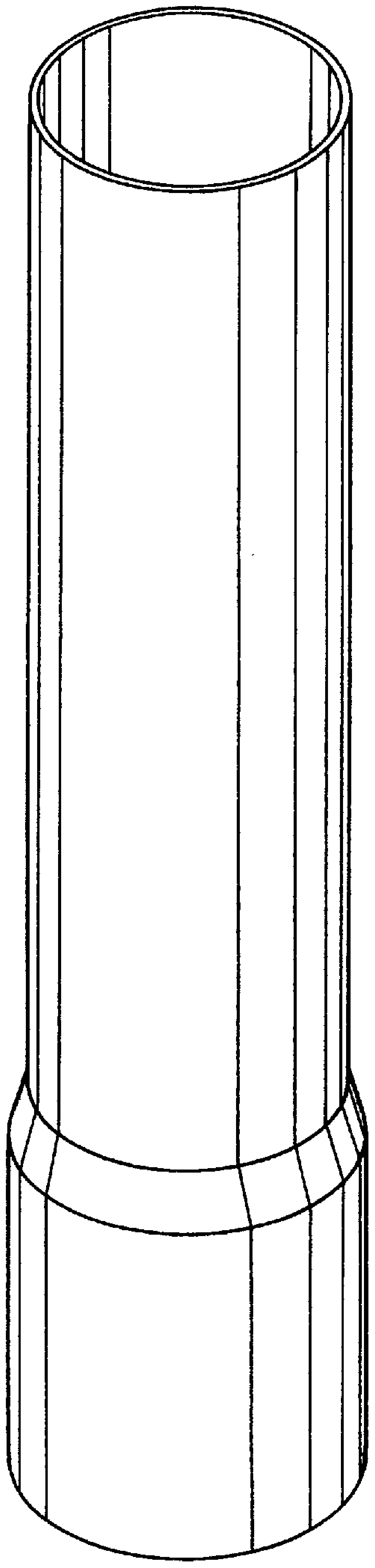

FIG. 2

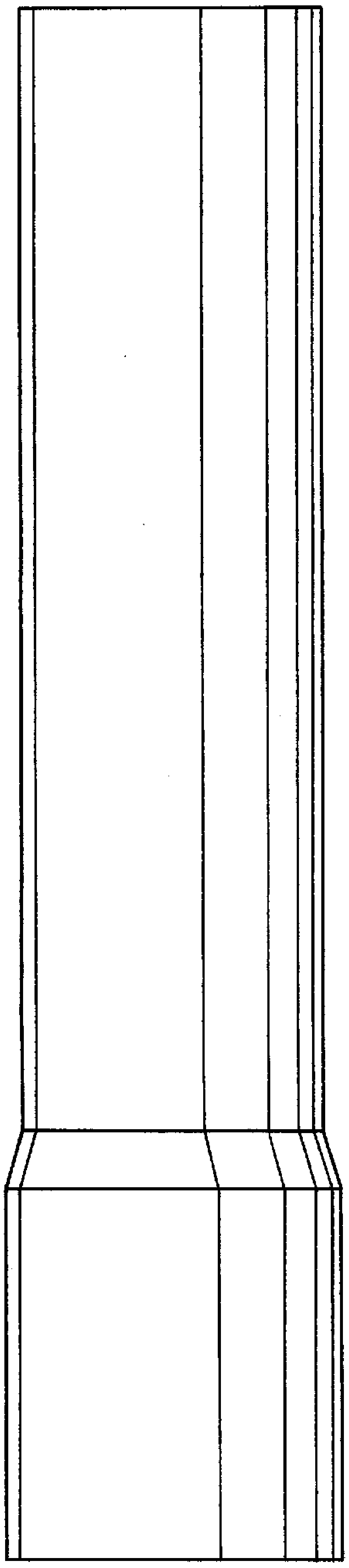

FIG. 3

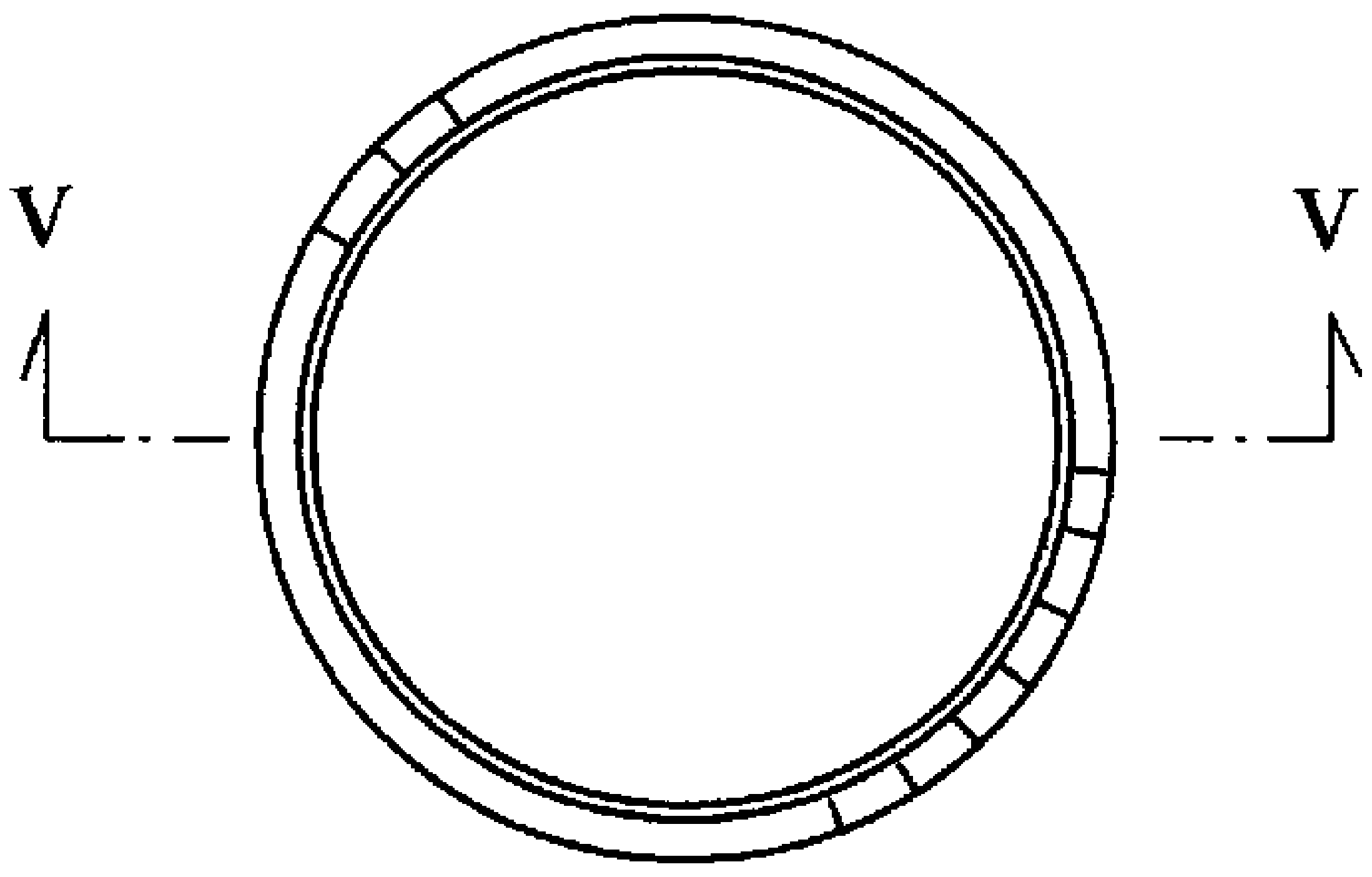

FIG. 4

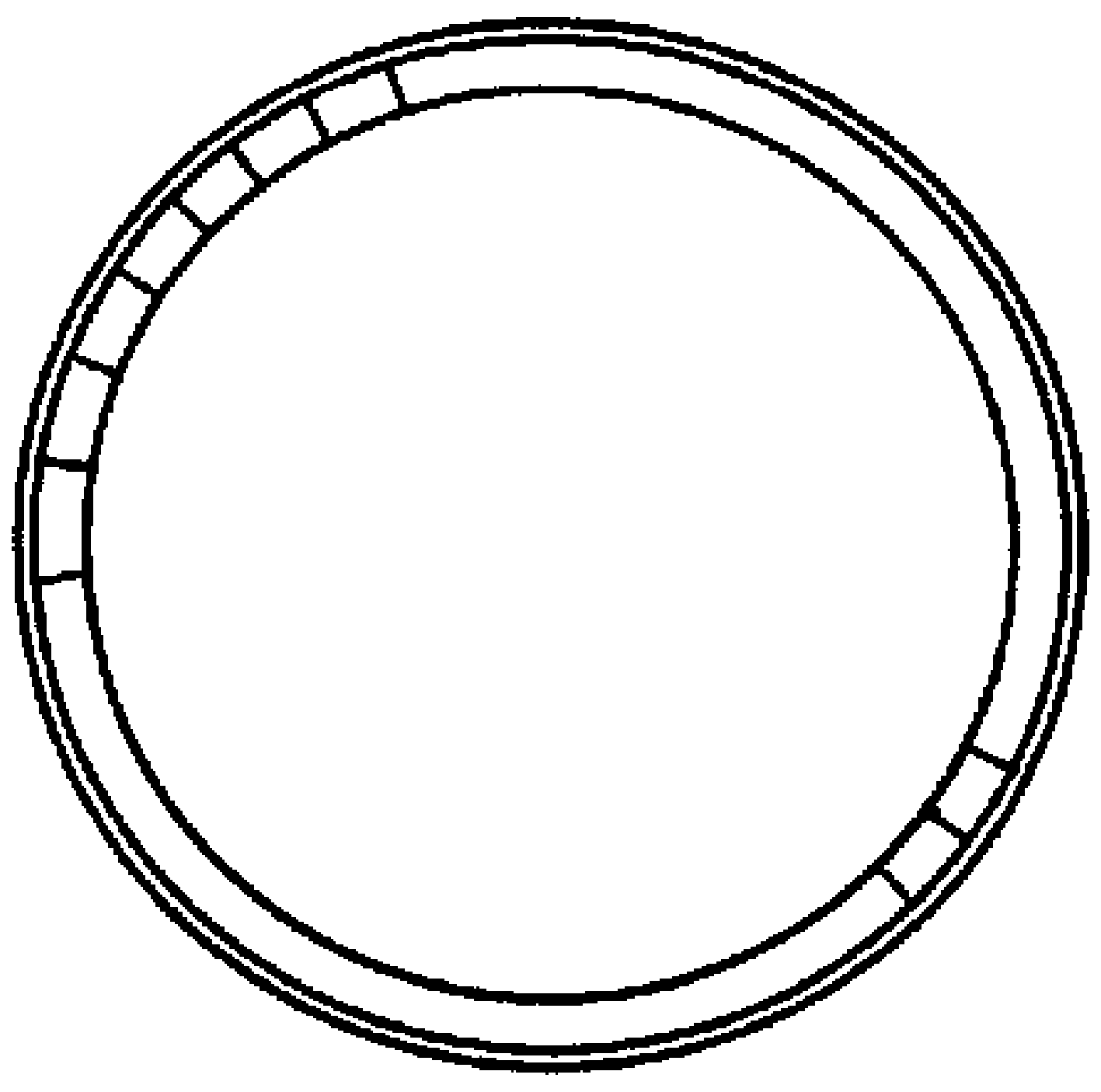

FIG. 5